



Kulicke & Soffa to Participate at SEMICON Korea 2018

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SINGAPORE--(BUSINESS WIRE)--Jan. 29, 2018-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the SEMICON Korea trade show in Seoul, South Korea, from January 31 through February 2, 2018.

Kulicke & Soffa will be at the SEMICON Korea trade show booth C400 Hall C, showcasing its latest equipment.

- **RAPID™ Pro** – the first in the latest *GEN-S* high performance wire bonders series, RAPID™ Pro delivers advanced process capabilities, real-time monitoring, diagnostics and traceability to ensure the highest quality and efficient assembly of automotive as well as other high performance semiconductor packages.
- **Asterion™** – built on an architecture with enhanced capabilities addresses the industry's growing and evolving power control and storage needs. A single platform handles a multitude of interconnect materials such as large aluminum wire, *PowerRibbon™* and interconnects for battery cells.
- **Hybrid Wafer Feeder** – an innovative solution that enables the combination of ultra-high-speed passive and active placement with high-accuracy flip-chip bonding directly from wafer is ideal for high-volume System-in-Package (SiP), flip-chip, die-attach and wafer-level-package manufacturing. Placement accuracy up to 7µm @ 3 sigma, provides a compelling alternative to existing commercial solutions.

"The latest Rapid™ Pro is the first *GEN-S Series* of bonder with the capabilities to deliver high yield and enable machine-to-machine communication. Kulicke & Soffa continues driving research and development investments delivering value-added features supporting the smart-manufacturing technology and improving the operational efficiency of customers," said Nelson Wong, Kulicke & Soffa's Senior Vice President, Ball Bonder Business Unit.

K&S consumable products including Quantis™ QFN and TeraCap™ capillaries, as well as FCC™ Plus and Opto™ Plus dicing blades, will also be featured at the trade show.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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